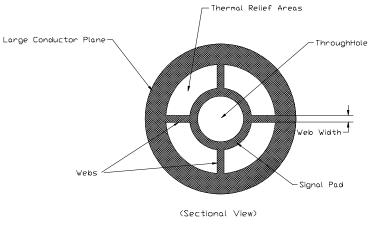


<u>Recommendation:</u> Thermal relief is required for all connections to large copper plane, this applies to all PTH and SMD (two pin device). Recommended thermal relief design is shown below:



Thermal Relief Within Conductor Planes

For proper thermal relief four spokes should be used. The preferred spoke widths are found in the table below. Other spoke patterns and sizes are acceptable upon approval of manufacturing and the appropriate design group. Caution should be used on large layer count boards. Multiple ground planes in a stack-up provide more thermal conductivity; therefore requiring a reduction in spoke width or number of spokes.

Signal Pad Size inches	Spoke Width inches
<0.0350 (0.89mm)	0.0078 (0.2mm)
0.0354 (0.9mm) -0.0448 (1.14mm)	0.0098 (0.25mm)
0.0460 (1.17mm) -0.0551 (1.40mm)	0.0118 (0.3mm)
0.0559 (1.42mm) -0.0720 (1.83mm)	0.0149 (0.38mm)
0.0728 (1.85mm) -0.0960 (2.44mm)	0.0181 (0.46mm)
0.0968 (2.46mm) -0.1200 (3.05mm)	0.0196 (0.5mm)
0.1208 (3.07mm) -0.2480 (6.3mm)	0.0314 (0.8mm)
>0.2480 (6.3mm)	0.0472 (1.2mm)

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